

General Multilayer Ceramic Capacitors



MLCC is an electronic part that temporarily stores an electrical charge and the most prevalent type of capacitor today. New technologies have enabled the MLCC manufacturers to follow the trend dictated by smaller and smaller electronic devices such as Cellular telephones, Computers, DSC, DVC

General Features

- Miniature Size
- Wide Capacitance and Voltage Range
- Tape & Reel for Surface Mount Assembly
- Low ESR

Applications

- General Electronic Circuit

Part Numbering

CL 10 B 104 K B 8 N N N C

- CL Samsung Multilayer Ceramic Capacitor
- 10 Size(mm)
- B Capacitance Temperature Characteristic
- 104 Nominal Capacitance
- K Capacitance Tolerance
- B Rated Voltage
- 8 Thickness Option
- N Product & Plating Method
- N Samsung Control Code
- N Reserved For Future Use
- C Packaging Type

CL Samsung Multilayer Ceramic Capacitor

SIZE(mm)

Code	EIA CODE	Size(mm)
03	0201	0.6 × 0.3
05	0402	1.0 × 0.5
10	0603	1.6 × 0.8
21	0805	2.0 × 1.25
31	1206	3.2 × 1.6
32	1210	3.2 × 2.5
43	1812	4.5 × 3.2
55	2220	5.7 × 5.0

④ CAPACITANCE TEMPERATURE CHARACTERISTIC

Code	Temperature Characteristics				Temperature Range
C	Class	COG	C	$0 \pm 30(\text{ppm}/^\circ\text{C})$	-55 ~ +125
P		P2H	P	-150 ± 60	
R		R2H	R	-220 ± 60	
S		S2H	S	-330 ± 60	
T		T2H	T	-470 ± 60	
U		U2J	U	-750 ± 60	
L		S2L	S	$+350 \sim -1000$	
A	Class	X5R	X5R	$\pm 15\%$	-55 ~ +85
B		X7R	X7R	$\pm 15\%$	-55 ~ +125
X		X6S	X6S	$\pm 22\%$	-55 ~ +105
F		Y5V	Y5V	$+22 \sim -82\%$	-30 ~ +85

Temperature Characteristic

Temperature Characteristics	Below 2.0pF	2.2 ~ 3.9pF	Above 4.0pF	Above 10pF
CΔ	C0G	C0G	C0G	C0G
PΔ	-	P2J	P2H	P2H
RΔ	-	R2J	R2H	R2H
SΔ	-	S2J	S2H	S2H
TΔ	-	T2J	T2H	T2H
UΔ	-	U2J	U2J	U2J

J : $\pm 120\text{PPM}/^\circ\text{C}$, H : $\pm 60\text{PPM}/^\circ\text{C}$, G : $\pm 30\text{PPM}/^\circ\text{C}$

④ NOMINAL CAPACITANCE

Nominal capacitance is identified by 3 digits.

The first and second digits identify the first and second significant figures of the capacitance.

The third digit identifies the multiplier. 'R' identifies a decimal point.

● Example

Code	Nominal Capacitance
1R5	1.5pF
103	10,000pF, 10nF, 0.01 μF
104	100,000pF, 100nF, 0.1 μF

CAPACITANCE TOLERANCE

Code	Tolerance	Nominal Capacitance
A	$\pm 0.05\text{pF}$	Less than 10pF (Including 10pF)
B	$\pm 0.1\text{pF}$	
C	$\pm 0.25\text{pF}$	
D	$\pm 0.5\text{pF}$	
F	$\pm 1\text{pF}$	
F	$\pm 1\%$	More than 10pF
G	$\pm 2\%$	
J	$\pm 5\%$	
K	$\pm 10\%$	
M	$\pm 20\%$	
Z	+80, -20%	

RATED VOLTAGE

Code	Rated Voltage	Code	Rated Voltage
R	4.0V	D	200V
Q	6.3V	E	250V
P	10V	G	500V
O	16V	H	630V
A	25V	I	1,000V
L	35V	J	2,000V
B	50V	K	3,000V
C	100V		

THICKNESS OPTION

Size	Code	Thickness(T)	Size	Code	Thickness(T)
0201(0603)	3	0.30±0.03	1812(4532)	F	1.25±0.20
0402(1005)	5	0.50±0.05		H	1.6±0.20
0603(1608)	8	0.80±0.10		I	2.0±0.20
0805(2012)	A	0.65±0.10		J	2.5±0.20
	C	0.85±0.10		L	3.2±0.30
	F	1.25±0.10	2220(5750)	F	1.25±0.20
	Q	1.25±0.15		H	1.6±0.20
1206(3216)	C	0.85±0.15		I	2.0±0.20
	F	1.25±0.15		J	2.5±0.20
	H	1.6±0.20		L	3.2±0.30
1210(3225)	F	1.25±0.20			
	H	1.6±0.20			
	I	2.0±0.20			
	J	2.5±0.20			
	V	2.5±0.30			

General Capacitors

PRODUCT & PLATING METHOD

Code	Electrode	Termination	Plating Type
A	Pd	Ag	Sn_100%
N	Ni	Cu	Sn_100%
G	Cu	Cu	Sn_100%

SAMSUNG CONTROL CODE

Code	Description of the code	Code	Description of the code
A	Array (2-element)	N	Normal
B	Array (4-element)	P	Automotive
C	High - Q	L	LICC

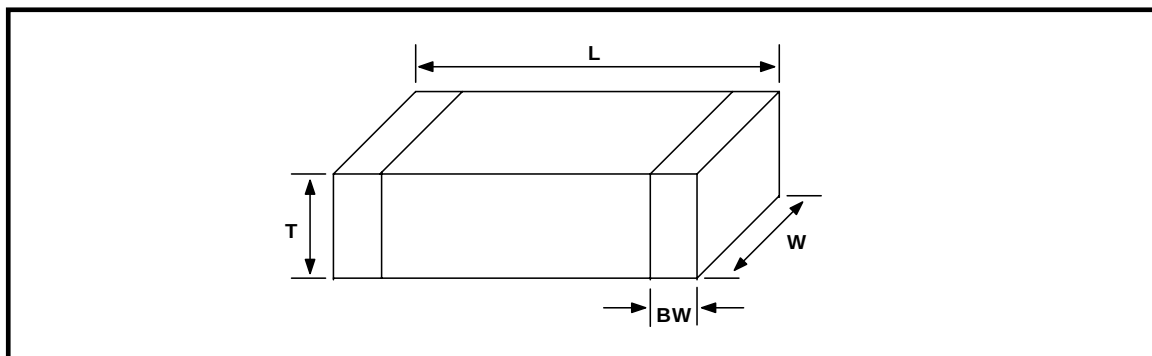
RESERVED FOR FUTURE USE

Code	Description of the code
N	Reserved for future use

PACKAGING TYPE

Code	Packaging Type	Code	Packaging Type
B	Bulk	F	Embossing 13" (10,000EA)
P	Bulk Case	L	Paper 13" (15,000EA)
C	Paper 7"	O	Paper 10"
D	Paper 13" (10,000EA)	S	Embossing 10"
E	Embossing 7"		

APPEARANCE AND DIMENSION

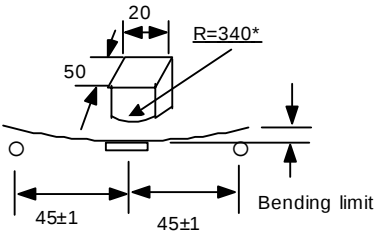


CODE	EIA CODE	DIMENSION (mm)			
		L	W	T (MAX)	BW
03	0201	0.6 ± 0.03	0.3 ± 0.03	0.33	0.15 ± 0.05
05	0402	1.0 ± 0.05	0.5 ± 0.05	0.55	0.2 +0.15/-0.1
10	0603	1.6 ± 0.1	0.8 ± 0.1	0.9	0.3 ± 0.2
21	0805	2.0 ± 0.1	1.25 ± 0.1	1.35	0.5 +0.2/-0.3
31	1206	3.2 ± 0.15	1.6 ± 0.15	1.40	0.5 +0.2/-0.3
		3.2 ± 0.2	1.6 ± 0.2	1.8	0.5 +0.3/-0.3
32	1210	3.2 ± 0.3	2.5 ± 0.2	2.7	0.6 ± 0.3
		3.2 ± 0.4	2.5 ± 0.3	2.8	
43	1812	4.5 ± 0.4	3.2 ± 0.3	3.5	0.8 ± 0.3
55	2220	5.7 ± 0.4	5.0 ± 0.4	3.5	1.0 ± 0.3

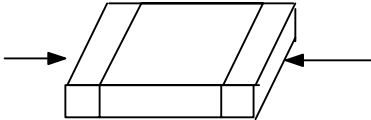
RELIABILITY TEST CONDITION

NO	ITEM		PERFORMANCE	TEST CONDITION		
1	Appearance		No Abnormal Exterior Appearance	Through Microscope(×10)		
2	Insulation Resistance		10,000MΩ or 500MΩ·μF whichever is smaller Rated Voltage is below 16V ; 10,000MΩ or 100MΩ·μF whichever is smaller	Apply the Rated Voltage For 60 ~ 120 Sec.		
3	Withstanding Voltage		No Dielectric Breakdown or Mechanical Breakdown	Class : 300% of the Rated Voltage for 1~5 sec. Class :250% of the Rated Voltage for 1~5 sec. is applied with less than 50mA current		
4	Capacitance	Class	Within the specified tolerance	Capacitance	Frequency	Voltage
				≤ 1,000pF	1kHz ±10%	0.5 ~ 5 Vrms
				>1,000pF	1kHz ±10%	
		Class	Within the specified tolerance	Capacitance	Frequency	Voltage
				≤ 10μF	1kHz ±10%	1.0±0.2Vrms
				>10μF	120Hz±20%	0.5±0.1Vrms
5	Q	Class	Capacitance ≥ 30pF : Q ≥ 1,000 			

RELIABILITY TEST CONDITION

NO	ITEM		PERFORMANCE		TEST CONDITION	
7	Temperature Characteristics of Capacitance	Class			Capacitance shall be measured by the steps shown in the following table.	
			Characteristics	Temp. Coefficient (PPM/)		
			C0G	0 ± 30		
			PH	-150 ± 60		
RH			-220 ± 60			
SH			-330 ± 60			
TH			-470 ± 60			
UL			-750 ± 120			
SL	+350 ~ -1000					
	Class			(1) Class		
				Temperature Coefficient shall be calculated from the formula as below.		
				Temp. Coefficient = $\frac{C2 - C1}{C1 \times T} \times 10^6$ [ppm/]		
				C1; Capacitance at step 3 C2: Capacitance at 85 T: 60 (=85 -25)		
	Class			(2) CLASS		
				Capacitance Change shall be calculated from the formula as below.		
				$C = \frac{C2 - C1}{C1} \times 100(\%)$		
				C1; Capacitance at step 3 C2: Capacitance at step 2 or 4		
8	Adhesive Strength of Termination		No Indication Of Peeling Shall Occur On The Terminal Electrode.	Apply 500g.f * Pressure for 10±1 sec. * 200g.f for 0201 case size.		
9	Bending Strength	Apperance	No mechanical damage shall occur.		Bending limit ; 1mm Test speed ; 1.0mm/SEC.	
		Capacitance	Characteristics	Capacitance Change	Keep the test board at the limit point in 5 sec., Then measure capacitance.	
			Class I	Within ±5% or ± 0.5 pF whichever is larger		
			Class II	A(X5R)/ B(X7R)/ X(X6S)	Within ±12.5%	
				F(Y5V)	Within ±30%	

RELIABILITY TEST CONDITION

NO	ITEM		PERFORMANCE		TEST CONDITION													
10	Solderability		More Than 95% of the terminal surface is to be soldered newly, So metal part does not come out or dissolve 		Solder	Sn-3Ag-0.5Cu	63Sn-37Pb											
					Solder Temp.	245±5	235±5											
					Flux	RMA Type												
					Dip Time	3±0.3 sec.	5±0.5 sec.											
					Pre-heating	at 80~120 for 10~30 sec.												
11	Resistance to Soldering heat	Apperance	No mechanical damage shall occur.		Solder Temperature : 270±5													
		Capacitance	Characteristics		Capacitance Change		Dip Time : 10±1 sec.											
			Class		Within ±2.5% or ±0.25pF whichever is larger		Each temination shall be fully immersed and preheated as below :											
			Class	A(X5R)/B(X7R)	Within ±7.5%		<table><tr><th>STEP</th><th>TEMP.()</th><th>TIME(SEC.)</th></tr><tr><td>1</td><td>80~100</td><td>60</td></tr><tr><td>2</td><td>150~180</td><td>60</td></tr></table>			STEP	TEMP.()	TIME(SEC.)	1	80~100	60	2	150~180	60
				STEP	TEMP.()	TIME(SEC.)												
				1	80~100	60												
		2	150~180	60														
		X(X6S)	Within ±15%															
		F	Within ±20%															
		Q (Class)	Capacitance ≥ 30pF : Q≥ 1000 															

RELIABILITY TEST CONDITION

NO	ITEM	PERFORMANCE	TEST CONDITION
13	Humidity (Steady State)	Appearance	No mechanical damage shall occur.
		Capacitance	Characteristics
			Capacitance Change
			Class
			Within $\pm 5.0\%$ or $\pm 0.5\text{pF}$ whichever is larger
		Class	A(X5R)/ B(X7R)/ X(X6S)
			Within $\pm 12.5\%$
14	Moisture Resistance	Q CLASS	Capacitance $\geq 30\text{pF}$: $Q \geq 350$ 10 $\leq$ Capacitance $< 30\text{pF}$: $Q \geq 275 + 2.5 \times C$ Capacitance $< 10\text{pF}$: $Q \geq 200 + 10 \times C$ (C: Capacitance)
			1. Characteristic : A(X5R), B(X7R) 0.05max (16V and over) 0.075max (10V) 0.075max (6.3V except Table 1) 0.125max* (refer to Table 1)
		Tan δ CLASS	2. Characteristic : F(Y5V) 0.075max (25V and over) 0.1max (16V, $C < 1.0\mu\text{F}$) 0.125max(16V, $C \geq 1.0\mu\text{F}$) 0.15max (10V) 0.195max (6.3V)
			Insulation Resistance
		Insulation Resistance	1,000 $\text{M}\Omega$ or 500 $\text{M}\Omega \cdot \mu\text{F}$ whichever is smaller.
			Applied Voltage : rated voltage Temperature : 40 ± 2 Humidity : 90~95%RH Duration Time : 500 +12/-0 Hr. Charge/Discharge Current : 50mA max.
		Q (Class)	Perform the initial measurement according to Note1.
			Perform the final measurement according to Note2.
14	Moisture Resistance	Capacitance	Characteristics
			Capacitance Change
			Class
			Within $\pm 5.0\%$ or $\pm 0.5\text{pF}$ whichever is larger
		Class	A(X5R)/ B(X7R)/ X(X6S)
			Within $\pm 12.5\%$ Within $\pm 12.5\%$ Within $\pm 30\%$
		Class	F(Y5V)
			Within $\pm 30\%$ Within $+30\% \sim -40\%$ In case of Table 2 *
14	Moisture Resistance	Q (Class)	Capacitance $\geq 30\text{pF}$: $Q \geq 200$ Capacitance $< 30\text{pF}$: $Q \geq 100 + 10/3 \times C$ (C: Capacitance)
			1. Characteristic : A(X5R), B(X7R) 0.05max (16V and over) 0.075max (10V) 0.075max (6.3V except Table 1) 0.125max* (refer to Table 1)
		Tan δ (Class)	2. Characteristic : F(Y5V) 0.075max (25V and over) 0.1max (16V, $C < 1.0\mu\text{F}$) 0.125max(16V, $C \geq 1.0\mu\text{F}$) 0.15max (10V) 0.195max (6.3V)
			X(X6S) 0.11max (6.3V and below)
		Insulation Resistance	500 $\text{M}\Omega$ or 250 $\text{M}\Omega \cdot \mu\text{F}$ whichever is smaller.
			Applied Voltage : rated voltage Temperature : 40 ± 2 Humidity : 90~95%RH Duration Time : 500 +12/-0 Hr. Charge/Discharge Current : 50mA max.
		Q (Class)	Perform the initial measurement according to Note1.
			Perform the final measurement according to Note2.

RELIABILITY TEST CONDITION

NO	ITEM	PERFORMANCE		TEST CONDITION
15	High Temperature Resistance	Appearance	No mechanical damage shall occur.	Applied Voltage : 200%* of the rated voltage Temperature : max. operating temperature Duration Time : 1000 +48/-0 Hr. Charge/Discharge Current : 50mA max. * refer to table(3) : 150%/100% of the rated voltage Perform the initial measurement according to Note1 for Class Perform the final measurement according to Note2.
		Capacitance	Characteristics	Capacitance Change
			Class	Within $\pm 3\%$ or $\pm 0.3\text{pF}$, Whichever is larger
			Class	A(X5R)/ B(X7R)
				Within $\pm 12.5\%$
				X(X6S)
			F(Y5V)	Within $\pm 25\%$
				Within $\pm 30\%$
16	Temperature Cycle	Q (Class)	Capacitance $\geq 30\text{pF}$: $Q \geq 350$ $10 \leq \text{Capacitance} < 30\text{pF}$: $Q \geq 275 + 2.5 \times C$ Capacitance $< 10\text{pF}$: $Q \geq 200 + 10 \times C$ (C: Capacitance)	
		Tan δ (Class)	1. Characteristic : A(X5R), B(X7R)	2. Characteristic : F(Y5V)
			0.05max (16V and over)	0.075max (25V and over)
			0.075max (10V)	0.1max(16V, $C < 1.0\mu\text{F}$)
			0.075max (6.3V except Table 1)	0.125max(16V, $C \geq 1.0\mu\text{F}$)
			0.125max* (refer to Table 1)	0.15max (10V)
			X(X6S) 0.11max (6.3V and below)	
		Insulation Resistance	1,000 M Ω or 50M Ω · μF whichever is smaller.	
16	Temperature Cycle	Appearance	No mechanical damage shall occur.	
		Capacitance	Characteristics	Capacitance Change
			Class	Within $\pm 2.5\%$ or $\pm 0.25\text{pF}$ Whichever is larger
			Class	A(X5R)/ B(X7R)/
				Within $\pm 7.5\%$
				X(X6S)
			F(Y5V)	Within $\pm 15\%$
		Q (Class)	Within the specified initial value	
		Tan δ (Class)	Within the specified initial value	
		Insulation Resistance	Within the specified initial value	

RELIABILITY TEST CONDITION

18	Recommended Soldering Method					
	Recommended Soldering Method By Size & Capacitance	Size inch (mm)	Temperature Characteristic	Capacitance	Condition	
					Flow	Reflow
		0201 (0603)	-	-	-	○
		0402 (1005)				
		0603 (1608)	Class I	-	○	○
			Class II	C < 1μF	○	○
				C ≥ 1μF	-	○
		0805 (2012)	Class I	-	○	○
			Class II	C < 4.7μF	○	○
C ≥ 4.7μF				-	○	
Array	-		-	○		
1206 (3216)	Class I	-	○	○		
	Class II	C < 10μF	○	○		
		C ≥ 10μF	-	○		
	Array	-	-	○		
1210 (3225)	-	-	-	○		
1808 (4520)				○		
1812 (4532)				○		
2220 (5750)				○		

Note1. Initial Measurement For Class

Perform the heat treatment at 150 $\pm$ 0/-10 for 1 hour. Then Leave the capacitor in ambient condition for 48 $\pm$ 4 hours before measurement. Then perform the measurement.

Note2. Latter Measurement

1. CLASS

Leave the capacitor in ambient condition for 24 $\pm$ 2 hours before measurement

Then perform the measurement.

2. Class

Perform the heat treatment at 150 $\pm$ 0/-10 for 1 hour. Then Leave the capacitor in ambient condition for 48 $\pm$ 4 hours before measurement.

Then perform the measurement.

*Table1.

Tan δ	0.125max*
Class A(X5R), B(X7R)	0201 C $\geq$ 0.022 μ F
	0402 C $\geq$ 0.22 μ F
	0603 C $\geq$ 2.2 μ F
	0805 C $\geq$ 4.7 μ F
	1206 C $\geq$ 10.0 μ F
	1210 C $\geq$ 22.0 μ F
	1812 C $\geq$ 47.0 μ F
	2220 C $\geq$ 100.0 μ F
All Low Profile Capacitors (P.16).	

*Table2.

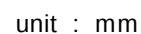
High Temperature Resistance test	
Δ C (Y5V)	+30 ~ - 40%
Class F(Y5V)	0402 C $\geq$ 0.47 μ F
	0603 C $\geq$ 2.2 μ F
	0805 C $\geq$ 4.7 μ F
	1206 C $\geq$ 10.0 μ F
	1210 C $\geq$ 22.0 μ F
	1812 C $\geq$ 47.0 μ F
	2220 C $\geq$ 100.0 μ F

*Table3.

High Temperature Resistance test		
Applied Voltage	100% of the rated voltage	150% of the rated voltage
Class A(X5R), B(X7R), X(X6S), F(Y5V)	0201 C $\geq$ 0.1 μ F	0201 C $\geq$ 0.022 μ F
	0402 C $\geq$ 1.0 μ F	0402 C $\geq$ 0.47 μ F
	0603 C $\geq$ 4.7 μ F	0603 C $\geq$ 2.2 μ F
	0805 C $\geq$ 22.0 μ F	0805 C $\geq$ 4.7 μ F
	1206 C $\geq$ 47.0 μ F	1206 C $\geq$ 10.0 μ F
	1210 C $\geq$ 100.0 μ F	1210 C $\geq$ 22.0 μ F
	All Low Profile Capacitors (P.16).	1812 C $\geq$ 47.0 μ F
		2220 C $\geq$ 100.0 μ F

Note3. All Size In Reliability Test Condition Section is "inch"

- **CARDBOARD PAPER TAPE (4mm)**



Symbol		A	B	W	F	E	P1	P2	P0	D	t
Type											
D i m e n s i o n	0603 (1608)	1.1 ±0.2	1.9 ±0.2	8.0 ±0.3	3.5 ±0.05	1.75 ±0.1	4.0 ±0.1	2.0 ±0.05	4.0 ±0.1	Φ1.5 +0.1/-0	1.1 Below
	0805 (2012)	1.6 ±0.2	2.4 ±0.2								
	1206 (3216)	2.0 ±0.2	3.6 ±0.2								

- **CARDBOARD PAPER TAPE (2mm)**

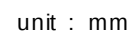
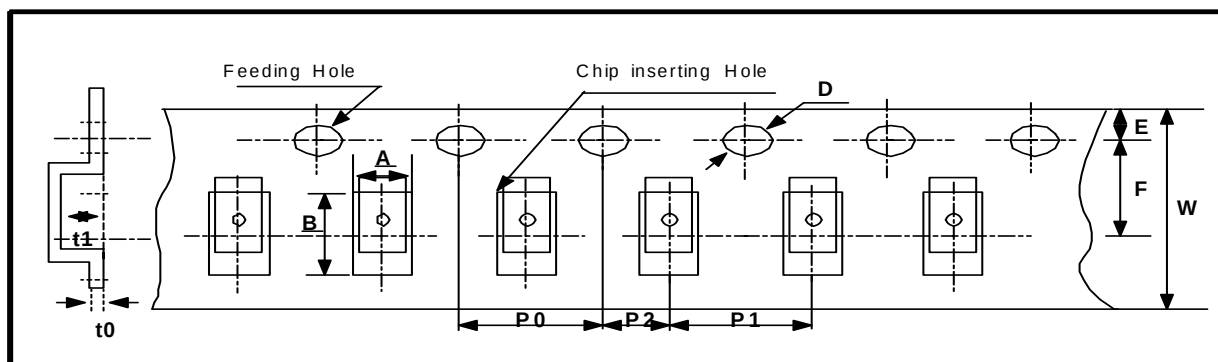


Table 1: Data											
Symbol		A	B	W	F	E	P1	P2	P0	D	t
Type											
D i m e n s i o n	0201 (0603)	0.38 ±0.03	0.68 ±0.03	8.0 ±0.3	3.5 ±0.05	1.75 ±0.1	2.0 ±0.05	2.0 ±0.05	4.0 ±0.1	Φ1.5 +0.1/-0.03	0.37 ±0.03
	0402 (1005)	0.62 ±0.04	1.12 ±0.04								0.6 ±0.05

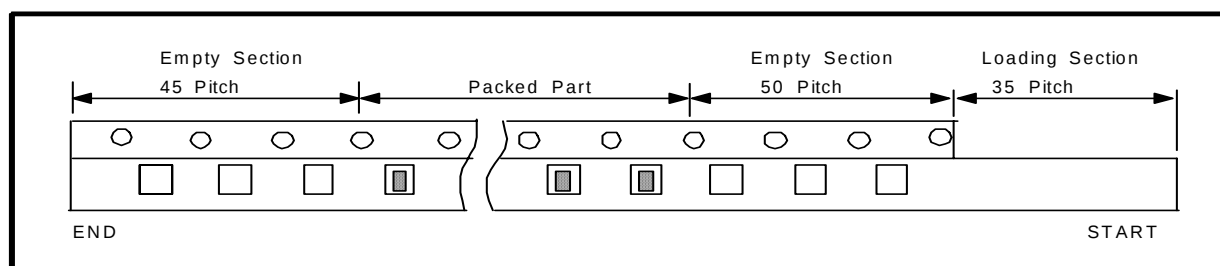
- **EMBOSSSED PLASTIC TAPE**



General Capacitors

Table 1. mm												
Symbol		A	B	W	F	E	P1	P2	P0	D	t1	t0
Type												
D i m e n s i o n	0805 (2012)	1.45 ±0.2	2.3 ±0.2	8.0 ±0.3	3.5 ±0.05	1.75 ±0.1	4.0 ±0.1	2.0 ±0.05	4.0 ±0.1	Φ1.5 +0.1/-0	2.5 max	0.6 Below
	1206 (3216)	1.9 ±0.2	3.5 ±0.2									
	1210 (3225)	2.9 ±0.2	3.7 ±0.2									
	1808 (4520)	2.3 ±0.2	4.9 ±0.2	12.0 ±0.3	5.60 ±0.05	8.0 ±0.1						
	1812 (4532)	3.6 ±0.2	4.9 ±0.2				3.8 max					
	2220 (5750)	5.5 ±0.2	6.2 ±0.2									

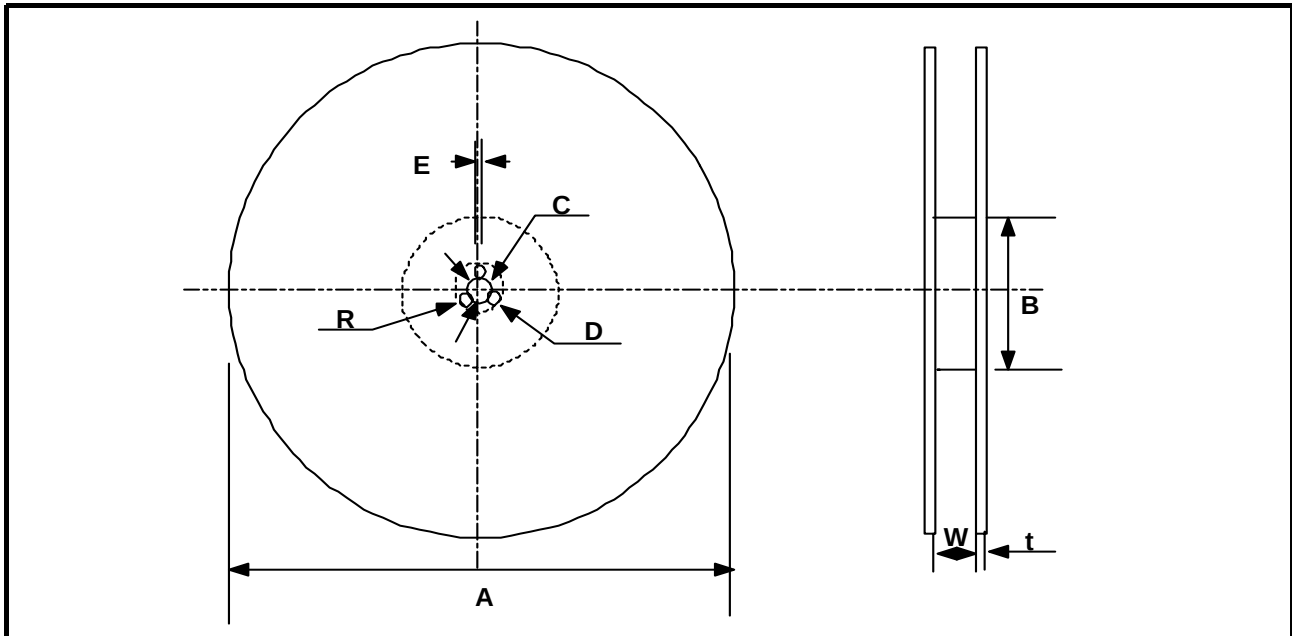
- **TAPING SIZE**



Type	Symbol	Size	Cardboard Paper Tape	Symbol	Size	Embossed Plastic Tape
7" Reel	C	0201(0603)	10,000	E	All Size ≤ 3216 1210(3225),1808(4520) ($t \leq 1.6\text{mm}$)	2,000
		0402(1005)	10,000		1210(3225)($t \geq 2.0\text{mm}$)	1,000
		OTHERS	4,000		1808(4520)($t \geq 2.0\text{mm}$)	1,000
10" Reel	O	-	10,000	-	-	-
13" Reel	D	0402(1005)	50,000	F	All Size ≤ 3216 1210(3225),1808(4520) ($t < 1.6\text{mm}$)	10,000
		OTHERS	10,000		1210(3225)($1.6 \leq t < 2.0\text{mm}$) 1206(3216)($1.6 \leq t$)	8,000
	L	0603(1608)	10,000 or 15,000		1210(3225),1808(4520) ($t \geq 2.0\text{mm}$)	4,000
		0805(2012)	15,000 or		1812(4532)($t \leq 2.0\text{mm}$)	4,000
		($t \leq 0.85\text{mm}$)	10,000(Option)		1812(4532)($t > 2.0\text{mm}$)	2,000
		1206(3216) ($t \leq 0.85\text{mm}$)	10,000		5750(2220)	

PACKAGING

• REEL DIMENSION

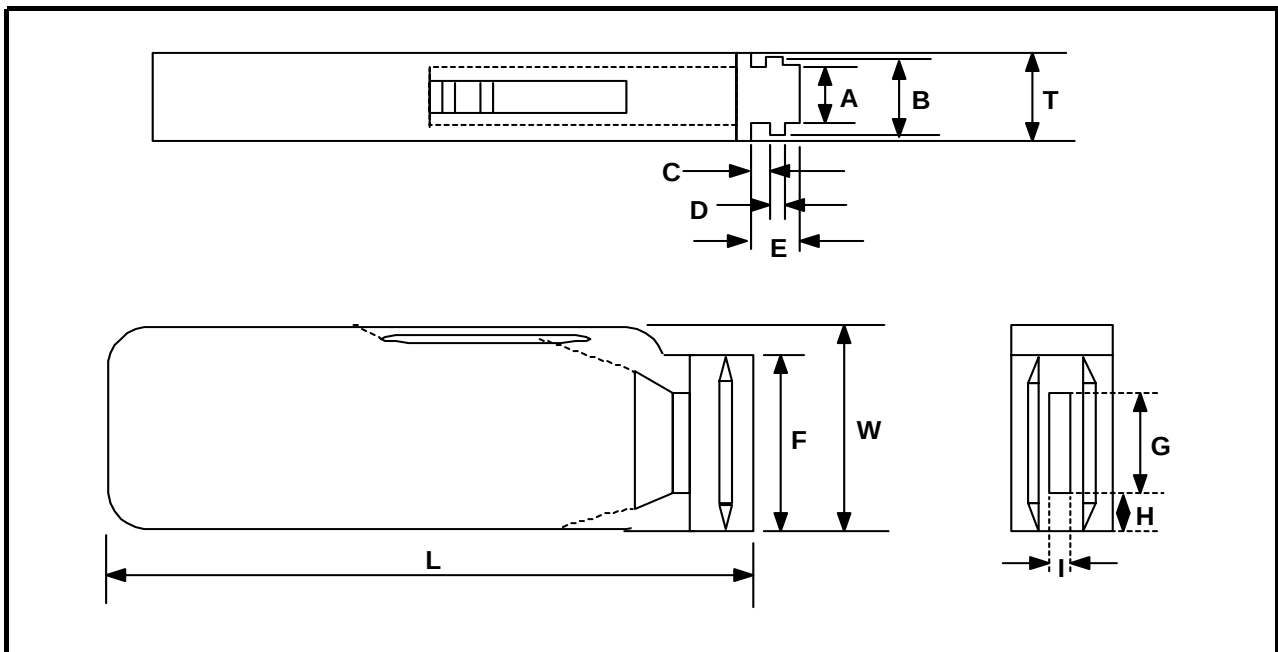


unit : mm

Symbol	A	B	C	D	E	W	t	R
7" Reel	$\phi 180+0/-3$	$\phi 60+1/-3$	$\phi 13 \pm 0.3$	25 ± 0.5	2.0 ± 0.5	9 ± 1.5	1.2 ± 0.2	1.0
13" Reel	$\phi 330 \pm 2.0$	$\phi 80+1/-3$					2.2 ± 0.2	

• BULK CASE PACKAGING

- Bulk case packaging can reduce the stock space and transportation costs.
- The bulk feeding system can increase the productivity.
- It can eliminate the components loss.



unit : mm

Symbol	A	B	T	C	D	E
Dimension	6.8 ± 0.1	8.8 ± 0.1	12 ± 0.1	$1.5 + 0.1/-0$	$2 + 0/-0.1$	$3.0 + 0.2/-0$

Symbol	F	W	G	H	L	I
Dimension	$31.5 + 0.2/-0$	$36 + 0/-0.2$	19 ± 0.35	7 ± 0.35	110 ± 0.7	5 ± 0.35

• QUANTITY OF BULK CASE PACKAGING

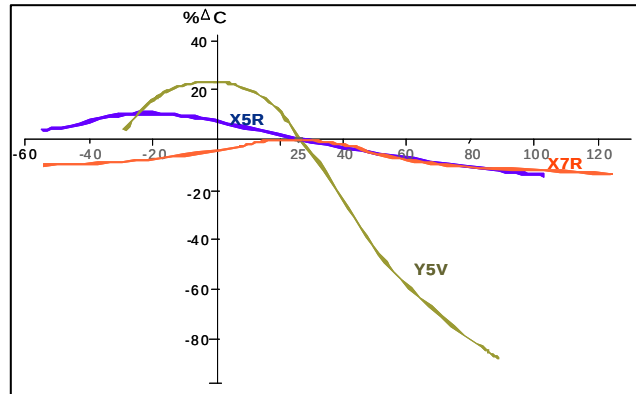
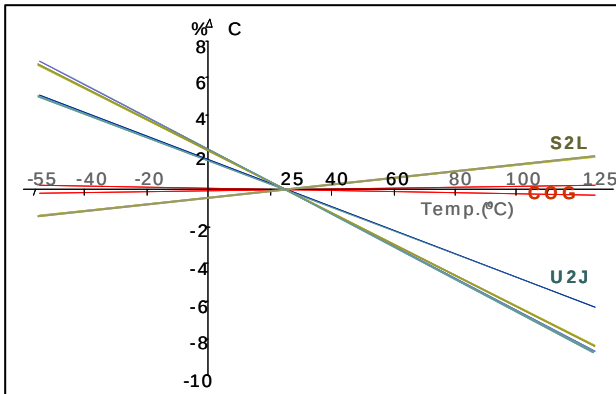
unit : pcs

Size	0402(1005)	0603(1608)	0805(2012)	
			T=0.65mm	T=0.85mm
Quantity	50,000	10,000 or 15,000	10,000	5,000 or 10,000

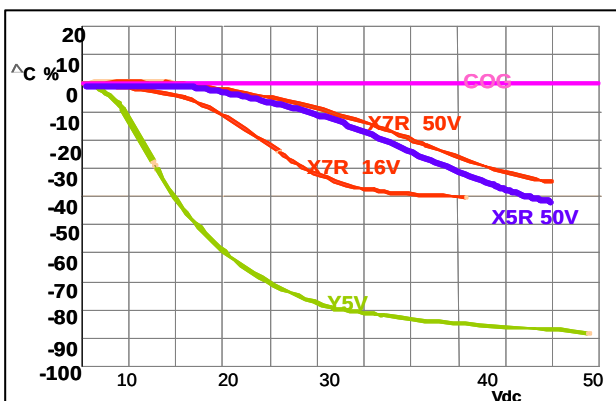
APPLICATION MANUAL

ELECTRICAL CHARACTERISTICS

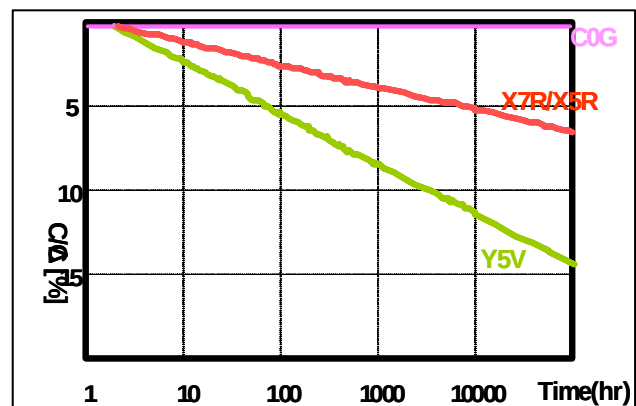
CAPACITANCE - TEMPERATURE CHARACTERISTICS



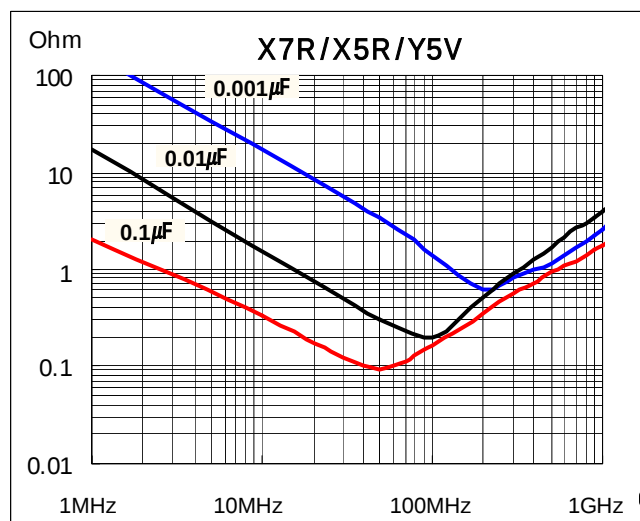
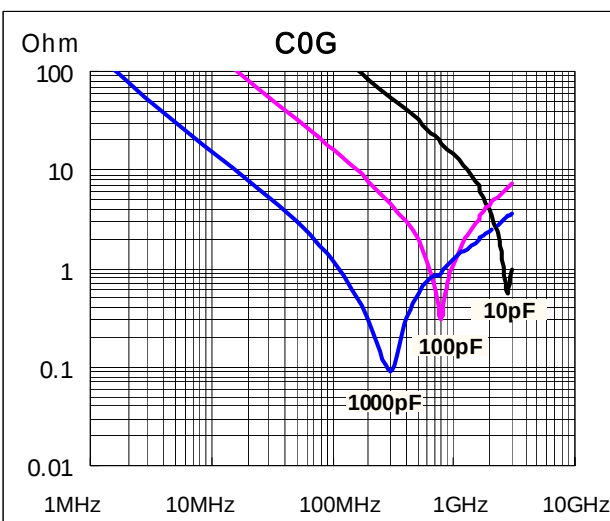
CAPACITANCE - DC VOLTAGE CHARACTERISTICS



CAPACITANCE CHANGE - AGING



IMPEDANCE - FREQUENCY CHARACTERISTICS



● STORAGE CONDITION

Storage Environment

The electrical characteristics of MLCCs were degraded by the environment of high temperature or humidity. Therefore, the MLCCs shall be stored in the ambient temperature and the relative humidity of less than 40 and 70%, respectively.

Guaranteed storage period is within 6 months from the outgoing date of delivery.

Corrosive Gases

Since the solderability of the end termination in MLCC was degraded by a chemical atmosphere such as chlorine, acid or sulfide gases, MLCCs must be avoid from these gases.

Temperature Fluctuations

Since dew condensation may occur by the differences in temperature when the MLCCs are taken out of storage, it is important to maintain the temperature-controlled environment.

● DESIGN OF LAND PATTERN

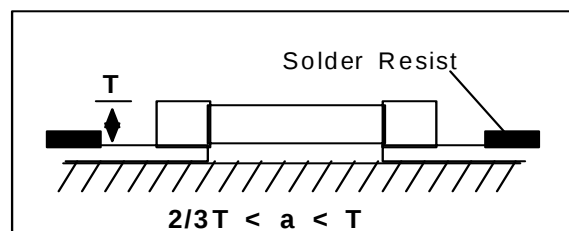
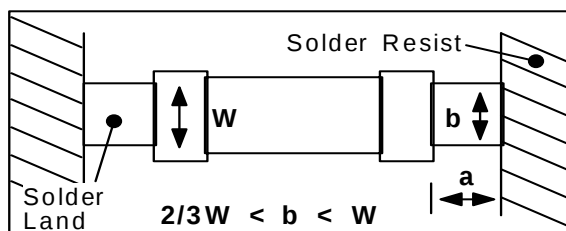
When designing printed circuit boards, the shape and size of the lands must allow for the proper amount of solder on the capacitor.

The amount of solder at the end terminations has a direct effect on the crack.

The crack in MLCC will be easily occurred by the tensile stress which was due to too much amount of solder. In contrast, if too little solder is applied, the termination strength will be insufficiently.

Use the following illustrations as guidelines for proper land design.

Recommendation of Land Shape and Size.



● ADHESIVES

When flow soldering the MLCCs, apply the adhesive in accordance with the following conditions.

Requirements for Adhesives

They must have enough adhesion, so that, the chips will not fall off or move during the handling of the circuit board.

They must maintain their adhesive strength when exposed to soldering temperature.

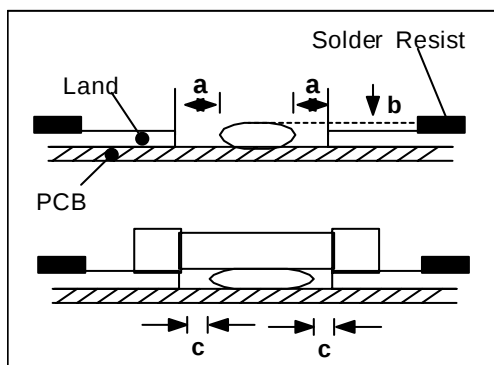
They should not spread or run when applied to the circuit board.

They should harden quickly. They should not corrode the circuit board or chip material.

They should be a good insulator. They should be non-toxic, and not produce harmful gases, nor be harmful when touched.

Application Method

It is important to use the proper amount of adhesive. Too little and much adhesive will cause poor adhesion and overflow into the land, respectively.



unit : mm

Type	21	31
a	0.2 min	0.2 min
b	70~100 μ m	70~100 μ m
c	> 0	> 0

Adhesive hardening Characteristics

To prevent oxidation of the terminations, the adhesive must harden at 160 or less, within 2 minutes or less.

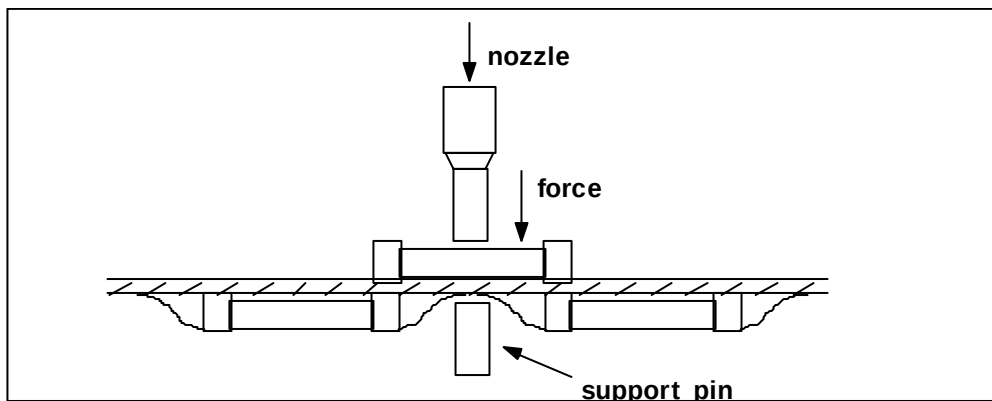
● MOUNTING

Mounting Head Pressure

Excessive pressure will cause crack to MLCCs. The pressure of nozzle will be 300g maximum during mounting.

Bending Stress

When double-sided circuit boards are used, MLCCs first are mounted and soldered onto one side of the board. When the MLCCs are mounted onto the other side, it is important to support the board as shown in the illustration. If the circuit board is not supported, the crack occur to the ready-installed MLCCs by the bending stress.



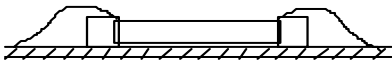
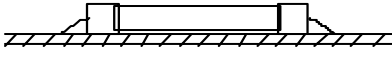
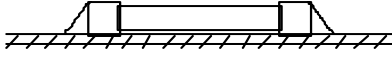
Manual Soldering

Manual soldering can pose a great risk of creating thermal cracks in chip capacitors.

The hot soldering iron tip comes into direct contact with the end terminations, and operator's carelessness may cause the tip of the soldering iron to come into direct contact with the ceramic body of the capacitor.

Therefore the soldering iron must be handled carefully, and close attention must be paid to the selection of the soldering iron tip and to temperature control of the tip.

Amount of Solder

Too much Solder		Cracks tend to occur due to large stress
Not enough Solder		Weak holding force may cause bad connections or detaching of the capacitor
Good		

Cooling

Natural cooling using air is recommended. If the chips are dipped into solvent for cleaning, the temperature difference(ΔT) must be less than 100

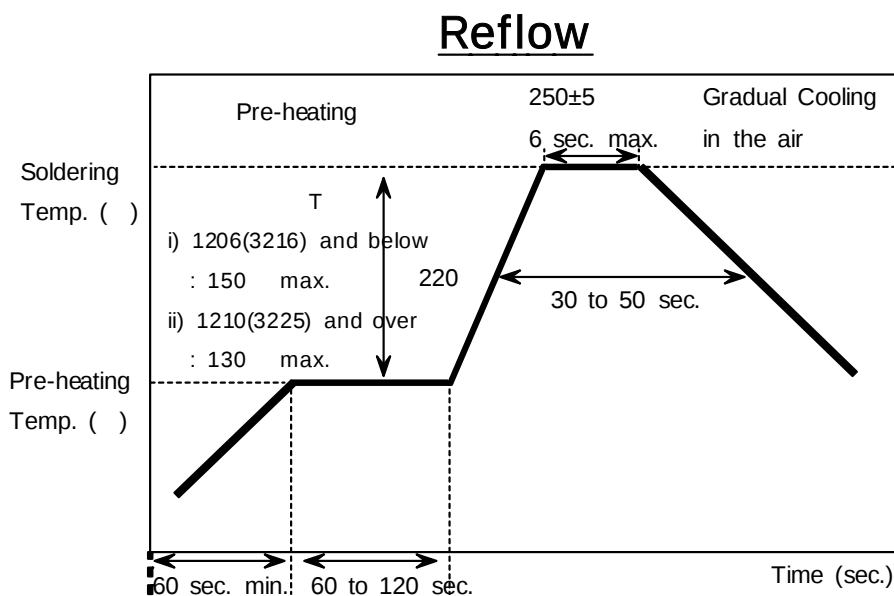
Cleaning

If rosin flux is used, cleaning usually is unnecessary. When strongly activated flux is used, chlorine in the flux may dissolve into some types of cleaning fluids, thereby affecting the chip capacitors. This means that the cleaning fluid must be carefully selected, and should always be new.

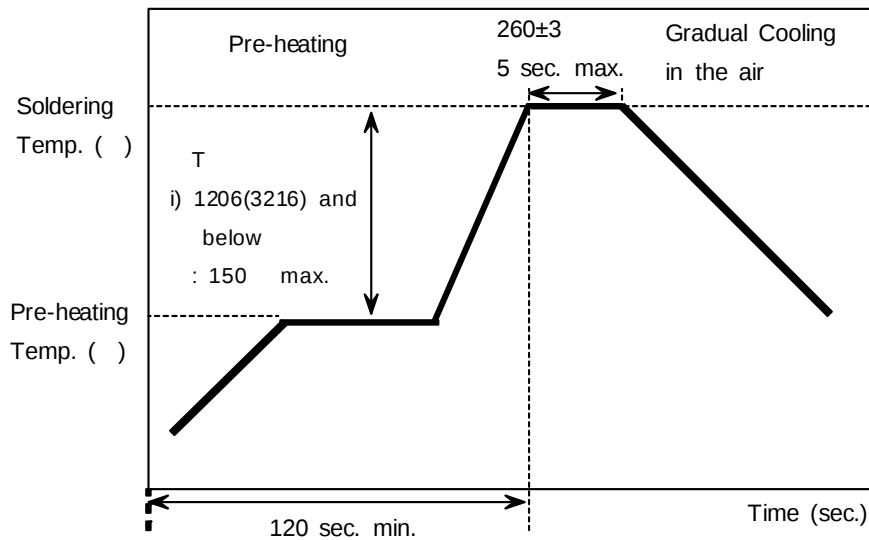
Notes for Separating Multiple, Shared PC Boards.

A multi-PC board is separated into many individual circuit boards after soldering has been completed. If the board is bent or distorted at the time of separation, cracks may occur in the chip capacitors. Carefully choose a separation method that minimizes the bending of circuit board.

Recommended Soldering Profile



Flow



Soldering Iron

Variation of Temp.	Soldering Temp ()	Pre-heating Time (Sec)	Soldering Time(Sec)	Cooling Time(Sec)
T≤130	300±10 max	≥ 60	≤ 4	-

Condition of Iron facilities		
Wattage	Tip Diameter	Soldering Time
20W Max	3mm Max	4 Sec Max

*** Caution - Iron Tip Should Not Contact With Ceramic Body Directly.**